**SOT-23-6L   20/-20V N+P Channel Enhancement 双沟道增强型 MOS Field Effect Transistor 场效应管**
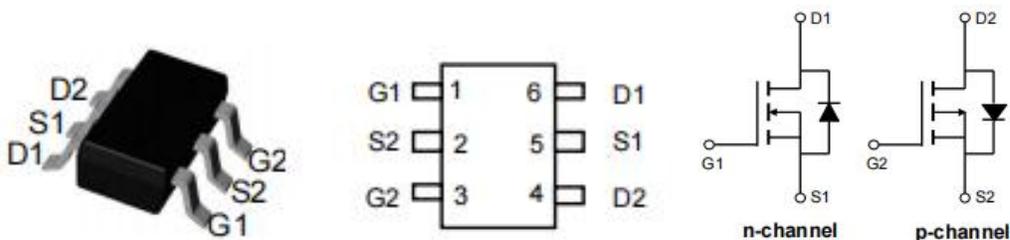
■**Absolute Maximum Ratings 最大额定值**

Characteristic 特性参数	Symbol 符号	Rat 额定值	Unit 单位
Drain-Source Voltage 漏极-源极电压	BV_{DSS}	20/-20	V
Gate- Source Voltage 栅极-源极电压	V_{GS}	$\pm10/\pm12$	V
Drain Current (continuous)漏极电流-连续	I_D（at $T_A = 25°C$）	3.5/-3.5	A
Drain Current (pulsed)漏极电流-脉冲	I_{DM}	13/-13	A
Total Device Dissipation 总耗散功率	P_D(at $T_A = 25°C$)	700/900	mW
Thermal Resistance Junction-Ambient 热阻	$R_{\Theta JA}$	178/140	℃/W
Junction/Storage Temperature 结温/储存温度	T_J, T_{stg}	-55~150	℃

■**Device Marking 产品字标**

FS6604=6604

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■Electrical Characteristics 电特性(N)

(T_A=25℃ unless otherwise noted 如无特殊说明，温度为25℃)

Characteristic 特性参数	Symbol 符号	Min 最小值	Typ 典型值	Max 最大值	Unit 单位
Drain-Source Breakdown Voltage 漏极-源极击穿电压(I_D=250uA,V_{GS}=0V)	BV_{DSS}	20	—	—	V
Gate Threshold Voltage 栅极开启电压(I_D=250uA,V_{GS}=V_{DS})	$V_{GS(th)}$	0.55	0.78	1.1	V
Zero Gate Voltage Drain Current 零栅压漏极电流(V_{GS}=0V, V_{DS}=20V)	I_{DSS}	—	—	1	uA
Gate Body Leakage 栅极漏电流(V_{GS}=±10V, V_{DS}=0V)	I_{GSS}	—	—	±100	nA
Static Drain-Source On-State Resistance 静态漏源导通电阻(I_D=3.5A,V_{GS}=4.5V) (I_D=2A,V_{GS}=2.5V)	$R_{DS(ON)}$	—	40 55	52 80	mΩ
Diode Forward Voltage Drop 内附二极管正向压降(I_{SD}=3.5A,V_{GS}=0V)	V_{SD}	—	—	1.2	V
Input Capacitance 输入电容 (V_{GS}=0V, V_{DS}=10V,f=1MHz)	C_{ISS}	—	220	—	pF
Common Source Output Capacitance 共源输出电容(V_{GS}=0V, V_{DS}=10V,f=1MHz)	C_{OSS}	—	34	—	pF
Reverse Transfer Capacitance 反馈电容(V_{GS}=0V, V_{DS}=10V,f=1MHz)	C_{RSS}	—	26	—	pF
Total Gate Charge 栅极电荷密度 (V_{DS}=10V, I_D=3A, V_{GS}=4.5V)	Q_g	—	3.6	—	nC
Gate Source Charge 栅源电荷密度 (V_{DS}=10V, I_D=3A, V_{GS}=4.5V)	Q_{gs}	—	0.9	—	nC
Gate Drain Charge 栅漏电荷密度 (V_{DS}=10V, I_D=3A, V_{GS}=4.5V)	Q_{gd}	—	0.8	—	nC
Turn-ON Delay Time 开启延迟时间 (V_{DS}=10V I_D=3A, R_{GEN}=3Ω,V_{GS}=4.5V)	$t_{d(on)}$	—	8	—	ns
Turn-ON Rise Time 开启上升时间 (V_{DS}=10V I_D=3A, R_{GEN}=3Ω,V_{GS}=4.5V)	t_r	—	58	—	ns
Turn-OFF Delay Time 关断延迟时间 (V_{DS}=10V I_D=3A, R_{GEN}=3Ω,V_{GS}=4.5V)	$t_{d(off)}$	—	15	—	ns
Turn-OFF Fall Time 关断下降时间 (V_{DS}=10V I_D=3A, R_{GEN}=3Ω,V_{GS}=4.5V)	t_f	—	53	—	ns

■Electrical Characteristics 电特性(P)

(T_A=25℃ unless otherwise noted 如无特殊说明，温度为 25℃)

Characteristic 特性参数	Symbol 符号	Min 最小值	Typ 典型值	Max 最大值	Unit 单位
Drain-Source Breakdown Voltage 漏极-源极击穿电压(I_D = -250uA, V_{GS}=0V)	BV_{DSS}	-20	—	—	V
Gate Threshold Voltage 栅极开启电压(I_D = -250uA, V_{GS}= V_{DS})	$V_{GS(th)}$	-0.4	-0.75	-1	V
Zero Gate Voltage Drain Current 零栅压漏极电流(V_{GS}=0V, V_{DS}= -20V)	I_{DSS}	—	—	1	uA
Gate Body Leakage 栅极漏电流(V_{GS}=±12V, V_{DS}=0V)	I_{GSS}	—	—	±100	nA
Static Drain-Source On-State Resistance 静态漏源导通电阻(I_D= -3.5A, V_{GS}= -4.5V) (I_D= -3A, V_{GS}= -2.5V)	$R_{DS(ON)}$	—	64 87	80 110	m Ω
Diode Forward Voltage Drop 内附二极管正向压降(I_{SD}= -3.5A, V_{GS}=0V)	V_{SD}	—	—	-1.2	V
Input Capacitance 输入电容 (V_{GS}=0V, V_{DS}= -10V,f=1MHz)	C_{ISS}	—	325	—	pF
Common Source Output Capacitance 共源输出电容(V_{GS}=0V, V_{DS}= -10V,f=1MHz)	C_{OSS}	—	63	—	pF
Reverse Transfer Capacitance 反馈电容(V_{GS}=0V, V_{DS}= -10V,f=1MHz)	C_{RSS}	—	37	—	pF
Total Gate Charge 栅极电荷密度 (V_{DS}= -10V, I_D= -2A, V_{GS}= -4.5V)	Q_g	—	3.2	—	nC
Gate Source Charge 栅源电荷密度 (V_{DS}= -10V, I_D= -2A, V_{GS}= -4.5V)	Q_{gs}	—	0.6	—	nC
Gate Drain Charge 栅漏电荷密度 (V_{DS}= -10V, I_D= -2A, V_{GS}= -4.5V)	Q_{gd}	—	0.9	—	nC
Turn-ON Delay Time 开启延迟时间 (V_{DS}= -10V I_D= -1A, R_{GEN}=2.5 Ω , V_{GS}= -4.5V)	$t_{d(on)}$	—	11	—	ns
Turn-ON Rise Time 开启上升时间 (V_{DS}= -10V I_D= -1A, R_{GEN}=2.5 Ω , V_{GS}= -4.5V)	t_r	—	5.5	—	ns
Turn-OFF Delay Time 关断延迟时间 (V_{DS}= -10V I_D= -1A, R_{GEN}=2.5 Ω , V_{GS}= -4.5V)	$t_{d(off)}$	—	22	—	ns
Turn-OFF Fall Time 关断下降时间 (V_{DS}= -10V I_D= -1A, R_{GEN}=2.5 Ω , V_{GS}= -4.5V)	t_f	—	8	—	ns
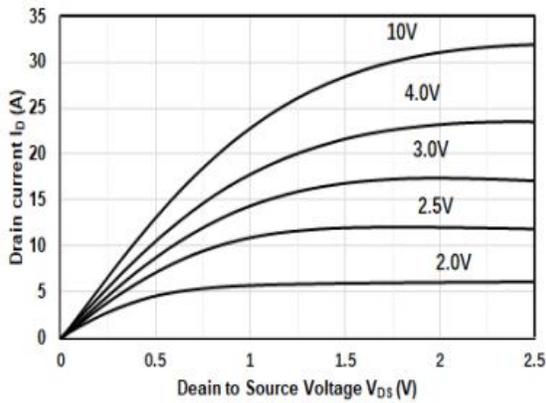
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## ■Typical Characteristic Curve 典型特性曲线(N)


Figure 1: Output Characteristics
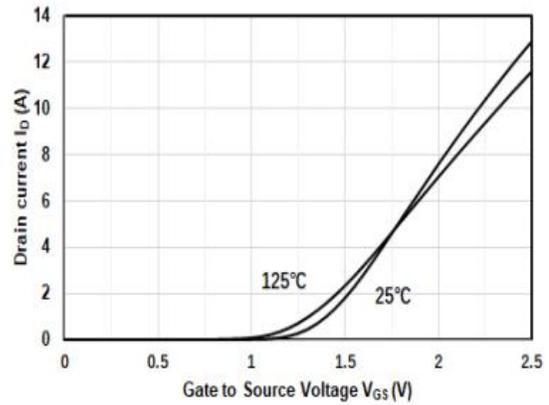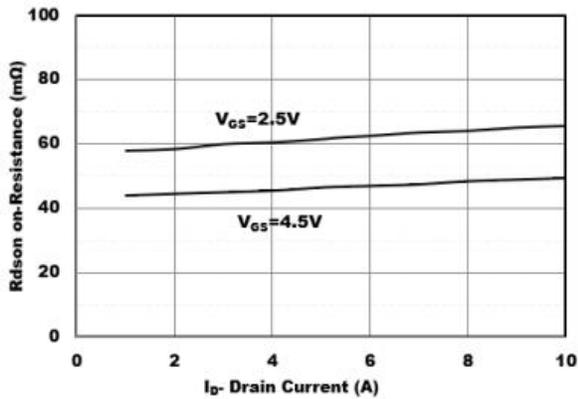

Figure 2: Transfer Characteristics

Figure 3: On-Resistance vs. Drain Current

Figure 4: Safe Operating Area

Figure 5: Capacitance Characteristics

Figure 6: Gate-Charge Characteristics

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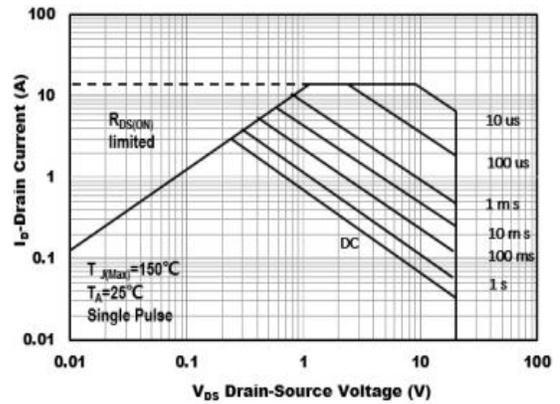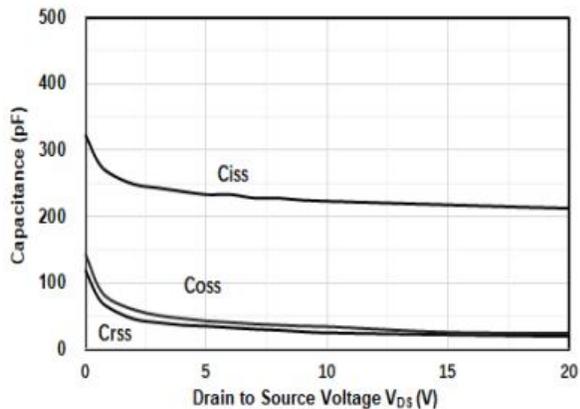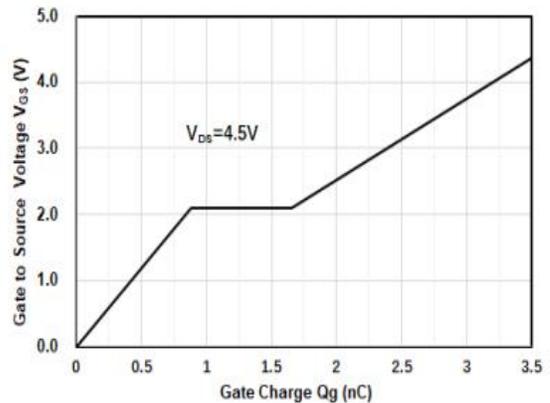
■**Typical Characteristic Curve 典型特性曲线(P)**

Figure 1: Output Characteristics
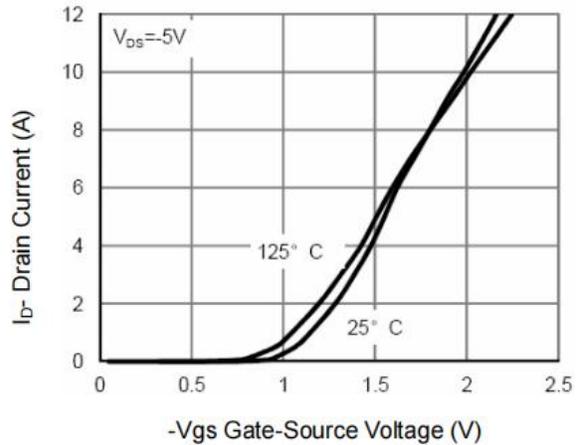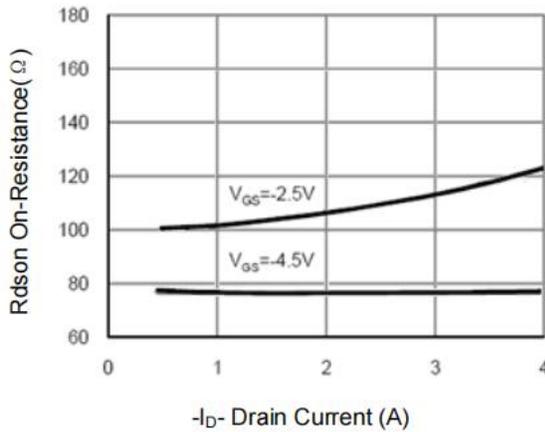
Figure 2: Transfer Characteristics

Figure 3: On-Resistance vs. Drain Current


Figure 4: Safe Operating Area

Figure 5: Capacitance Characteristics

Figure 6: Gate-Charge Characteristics

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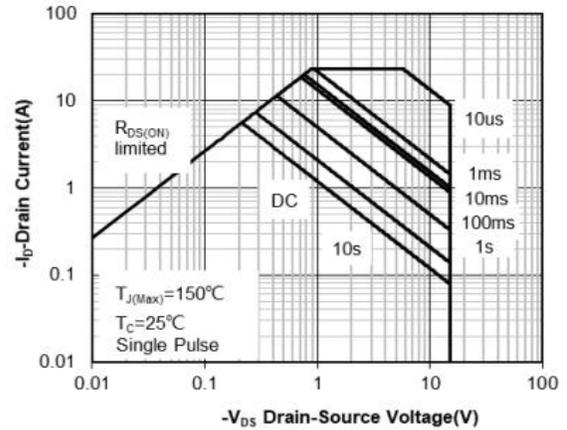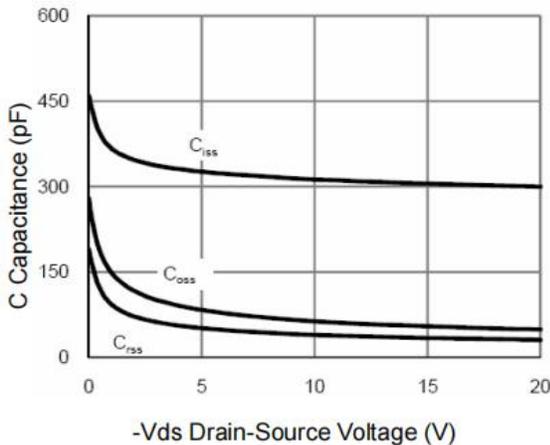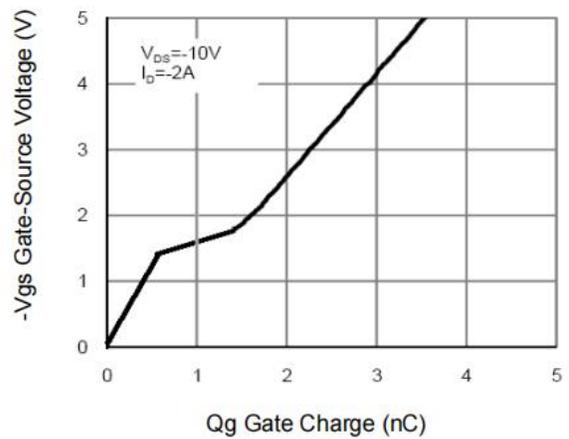
■Dimension 外形封装尺寸
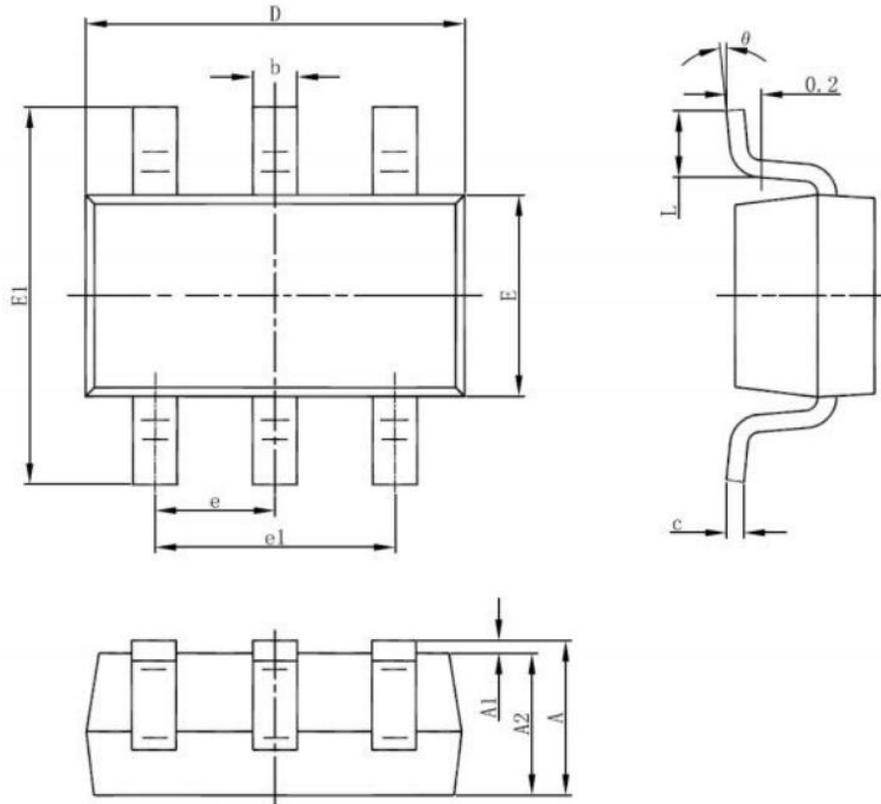
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.900	1.00	0.035	0.039
e1	1.800	2.000	0.071	0.079
L	0.450	0.650	0.018	0.026
L1	0.300	0.600	0.012	0.024
θ	0º	8º	0º	8º